

Excellent Integrated System Limited

Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Samsung Electro-Mechanics America, Inc.](#)
[CL31B225KPFNNNE](#)

For any questions, you can email us directly:

sales@integrated-circuit.com



**SAMSUNG
ELECTRO-MECHANICS**



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : **CL31B225KPFNNNE**
- Description : **CAP, 2.2 μ F, 10V, \pm 10%, X7R, 1206**

A. Samsung Part Number

CL
 31
 B
 225
 K
 P
 F
 N
 N
 N
 E
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	1206 (inch code)	L: 3.2 \pm 0.15 mm	W: 1.6 \pm 0.15 mm
③ Dielectric	X7R	⑧ Inner electrode	Ni
④ Capacitance	2.2 μ F	Termination	Cu
⑤ Capacitance tolerance	\pm 10 %	Plating	Sn 100% (Pb Free)
⑥ Rated Voltage	10 V	⑨ Product	Normal
⑦ Thickness	1.25 \pm 0.15 mm	⑩ Special	Reserved for future use
		⑪ Packaging	Embossed Type, 7" reel

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1kHz \pm 10% 1.0 \pm 0.2Vrms
Tan δ (DF)	0.05 max.	
Insulation Resistance	10,000Mohm or 100Mohm $\cdot\mu$ F Whichever is Smaller	Rated Voltage 60~120 sec.
Appearance	No abnormal exterior appearance	Microscope (\times 10)
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	250% of the rated voltage
Temperature Characterisitcs	X7R (From -55 $^{\circ}$ C to 125 $^{\circ}$ C, Capacitance change should be within \pm 15%)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g-F, for 10 \pm 1 sec.
Bending Strength	Capacitance change : within \pm 12.5%	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245 \pm 5 $^{\circ}$ C, 3 \pm 0.3sec. (preheating : 80~120 $^{\circ}$ C for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within \pm 7.5% Tan δ , IR : initial spec.	Solder pot : 270 \pm 5 $^{\circ}$ C, 10 \pm 1sec.

	Performance	Test condition
Vibration Test	Capacitance change : within $\pm 5\%$ Tan δ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours \times 3 direction (x, y, z)
Moisture Resistance	Capacitance change : within $\pm 12.5\%$ Tan δ : 0.075 max IR : 500Mohm or 25Mohm $\cdot \mu F$ Whichever is Smaller	With rated voltage 40 \pm 2 $^{\circ}$ C , 90~95%RH, 500+12/-0hrs
High Temperature Resistance	Capacitance change : within $\pm 12.5\%$ Tan δ : 0.075 max IR : 1000Mohm or 50Mohm $\cdot \mu F$ Whichever is Smaller	With 200% of the rated voltage Max. operating temperature 1000+48/-0hrs
Temperature Cycling	Capacitance change : within $\pm 7.5\%$ Tan δ , IR : initial spec.	1 cycle condition Min. operating temperatur \rightarrow 25 $^{\circ}$ C \rightarrow Max. operating temperature \rightarrow 25 $^{\circ}$ C 5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C , 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.